



# Elevated Temperature Board 850°

## **Elevated Temperature Board 850°**

#### Description

Knauf Elevated Temperature Board 850° is a lightweight insulation (2.8 PCF, 44.9 kg/m<sup>3</sup>) made from inorganic glass fibers bonded with a high-temperature thermosetting resin. It is a semi-rigid, board-like form with superior handling properties and insulating effectiveness at minimum cost.

#### Application

Knauf Elevated Temperature Board 850° is used for boiler walls, hot precipitators, hot ductwork, cylindrical tanks, towers, stacks and industrial ovens.

#### Features and Benefits Excellent Thermal Properties

Reduces operating cost.

#### **Low Installed Cost**

- · Lightweight.
- · Easy to fabricate.
- · Sizes up to 4' x 10' available.

#### **Polybag and Sleeve Packaging**

- Damage resistant.
- Reduces storage space.

#### **Resilient Fiber Glass**

Maintains integrity at elevated temperatures.

#### Specification Compliance In U.S.:

- · ASTM C 612; Type IA, IB, II
- ASTM C 795

- HH-I-558C (Amend. 3); Form A, Class 1, 2, 3
- · MIL-I-22023D; Type III
- MIL-I-24244C
- NRC Reg. Guide 1.36
- USCG 164.109/15/0

#### In Canada:

- CAN/ULC S102-M88
- CCG F1-315
- CGSB 51-GP-10M

#### Technical Data Surface Burning Characteristics

 Does not exceed 25 Flame Spread, 50 Smoke Developed when tested in accordance with ASTM E 84 and CAN/ULC S102-M88 and UL 723.

#### **Temperature Limitation (ASTM C 411)**

• Up to 850°F (454°C).

#### Alkalinity (ASTM C 871)

- Less than 0.6% as Na<sub>2</sub>O.
- pH between 7.5 and 12.0.

#### **Corrosiveness (ASTM C 665)**

- · Will not accelerate corrosion of steel.
- Microbial Growth (ASTM C 1338)
- · Does not support microbial growth.

### Application and Specification Guidelines

#### **Storage**

 Protect material from water damage or other abuse. Cartons are not designed for outside storage. Vacuum packaged material can be stored outside if care is taken not to puncture the polybag.

#### Preparation

Apply the product on clean, dry surfaces.

#### Application

- All insulation joints must be firmly butted. Mount flush against surfaces to 850°F (454°C) or use in panels mounted away from operating surface.
- Knauf ET Board 850° is designed to be applied over welded pins and/or studs up to 1/2" (13 mm) in diameter. The board is to be held in place by speed washers, tension clips or metal mesh reinforcement.
- Installation method should not compress material beyond maximum of 5% at any point.
- Pins and studs shall be located a maximum of 4" (102 mm) from each edge and spaced no greater than 16" (406 mm) on center.
- In temperatures over 550°F (288°C) and designed thickness over 3" (76 mm) dual layer application with staggered joints is recommended. Install thickness recommended by Knauf or NAIMA 3E Plus program.
- Finish surface with metal cover, or with insulating cement and canvas.

#### Precaution

- During initial heat-up to operating temperatures above 350°F (177°C), a slight odor and some smoke may be given off as a portion of the bonding material used in the insulation begins to undergo a controlled decomposition.
- If natural convection is not adequate in confined areas, forced ventilation should be provided in order to protect against any harmful fumes and vapors that might be generated.

#### Caution

Fiber glass may cause temporary skin irritation. Wear long-sleeved, loose-fitting clothing, head covering, gloves and eye protection when handling and applying material. Wash with soap and warm water after handling. Wash work clothes separately and rinse washer. A disposable mask designed for nuisance type dusts should be used where sensitivity to dust and airborne particles may cause irritation to the nose or throat.

#### **Thermal Efficiency (ASTM C 177)** .70 .101 Thermal Conductivity (BTU-in./hr $\cdot$ ft $^{2,\circ}$ F) Thermal Conductivity (SI Units ) (W/m ${\scriptstyle \bullet\,^\circ C})$ .60 .086 .50 072 .40 .057 .30 .043 .20 .029 0 -18 100 38 200 93 500 (°F) 260 (°C) 300 149 400 204 Mean Temperature Mean Temperature k(SI) k 100°F (38°C) .25 .036 200°F (93°C) .33 .048 300°F (149°C) .40 .058 .49 400°F (204°C) .071 500°F (260°C) .57 .082

#### Forms Available

Thickness		Width	Length
1"	(25 mm)		
1½"	(38 mm)		
2"	(51 mm)	24" (610 mm)	24" (1219 mm)
21⁄2"	(64 mm)	and	to
3"	(76 mm)	48" (1219 mm)	120" (3048 mm)
3½"	(89 mm)		
4"	(102 mm)		



• Knauf ET Board offers lightweight solutions with excellent handling properties.



Maintain integrity for applications at elevated temperatures up to 850°F.



Available in a wide variety of sizes and thicknesses.

For more information call (800) 825-4434, ext. 8283

or visit us online at www.KnaufInsulation.com





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#### **Fiber Glass and Mold**

Fiber glass insulation will not sustain mold growth. However, mold can grow on almost any material when it becomes wet and contaminated with organic materials. Carefully inspect any insulation that has been exposed to water. If it shows any sign of mold it must be discarded. If the material is wet but shows no evidence of mold, it should be dried rapidly and thoroughly. If it shows signs of facing degradation from wetting, it should be replaced.

#### Notes

The chemical and physical properties of Knauf Elevated Temperature Board 850° represent typical average values determined in accordance with accepted test methods. The data is subject to normal manufacturing variations. The data is supplied as a technical service and is subject to change without notice. References to numerical flame spread ratings are not intended to reflect hazards presented by these or any other materials under actual fire conditions.

Check with your Knauf sales representative to assure information is current.



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